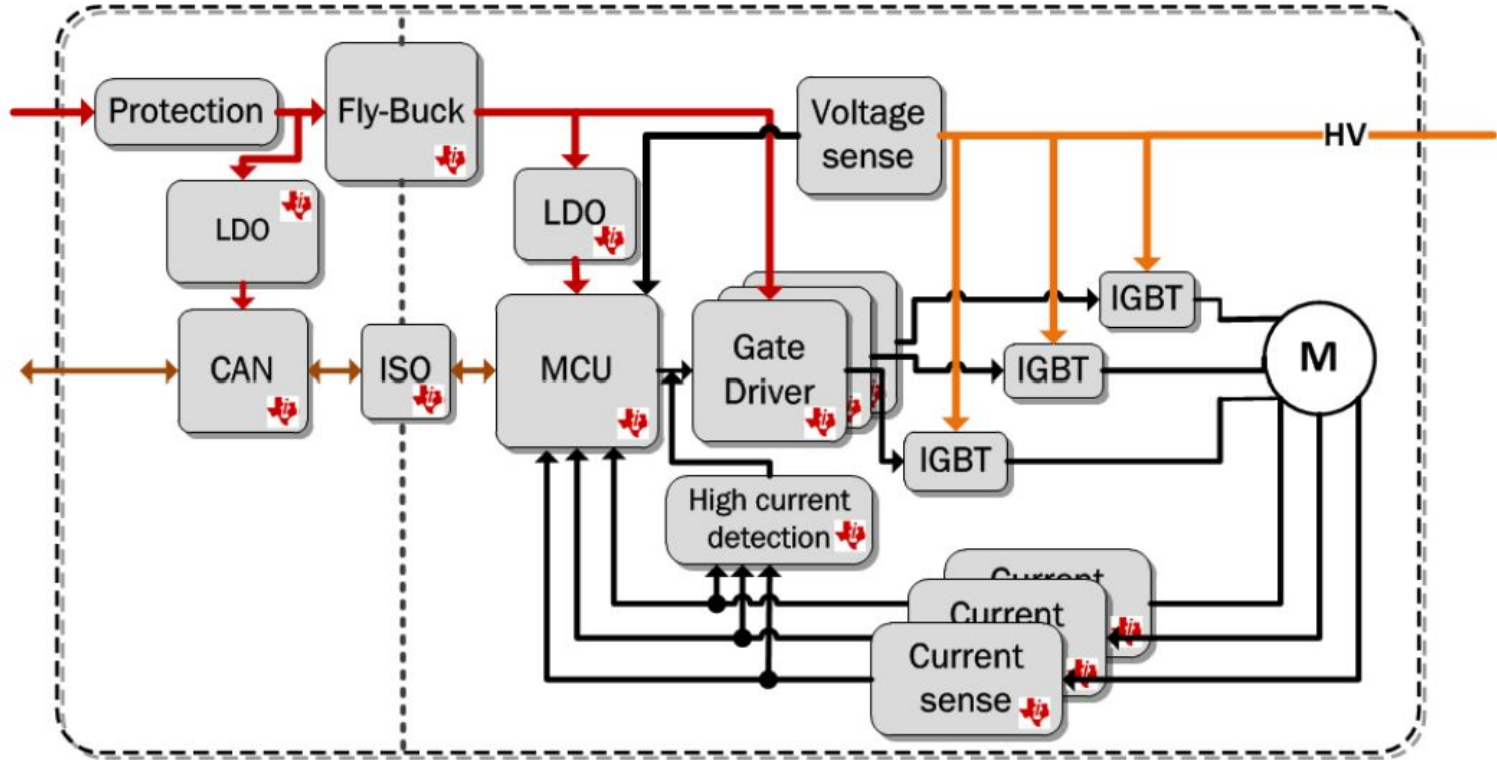
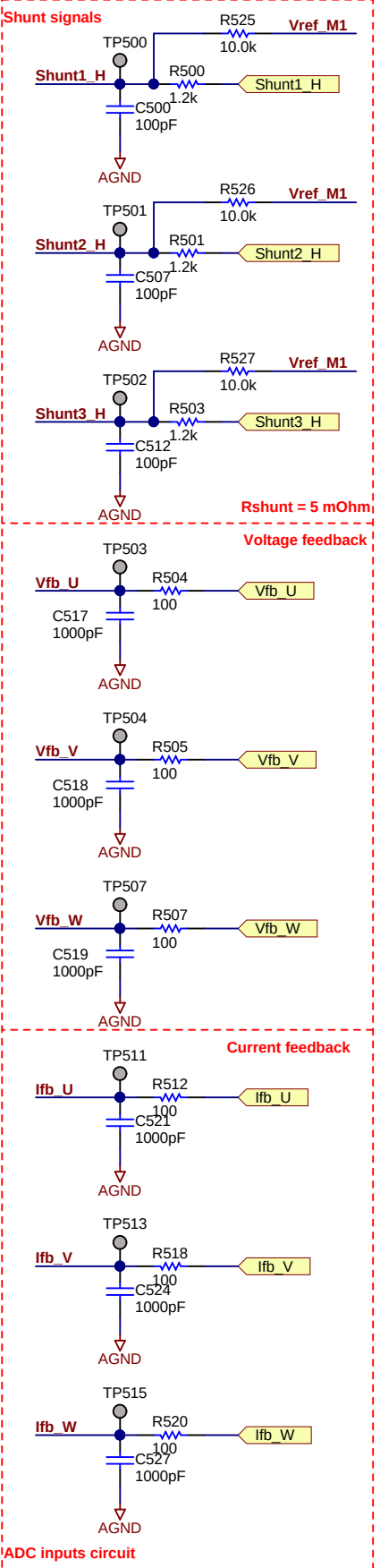
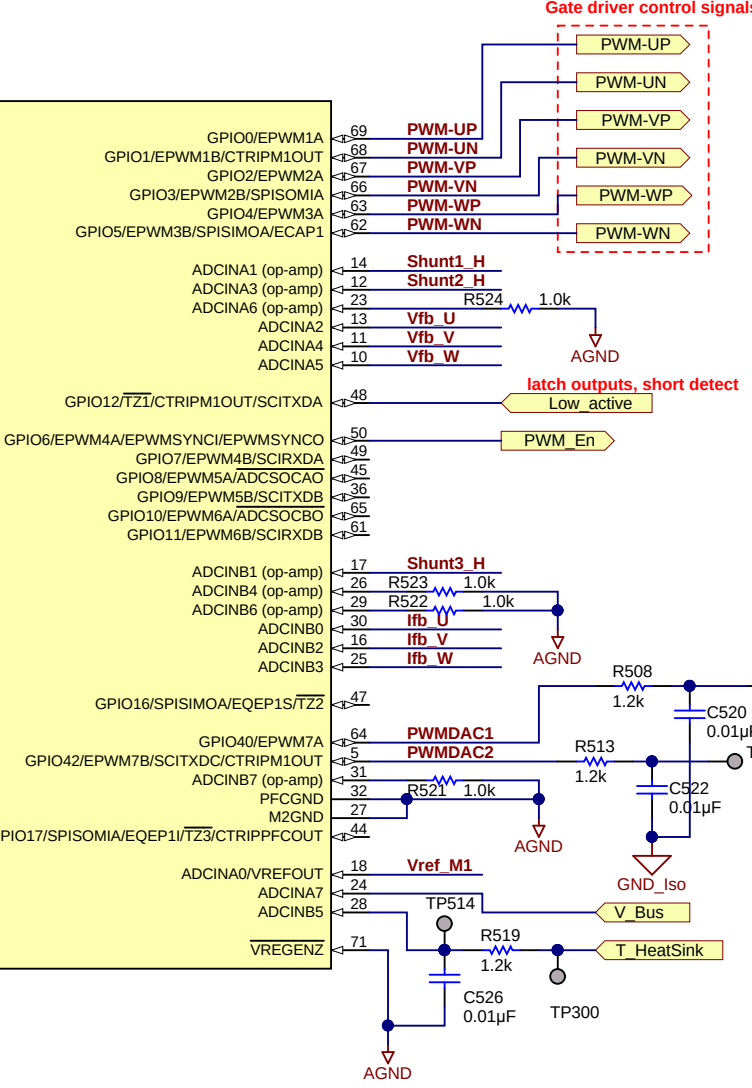
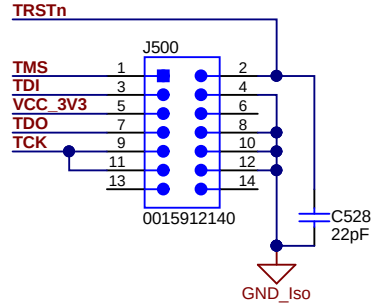
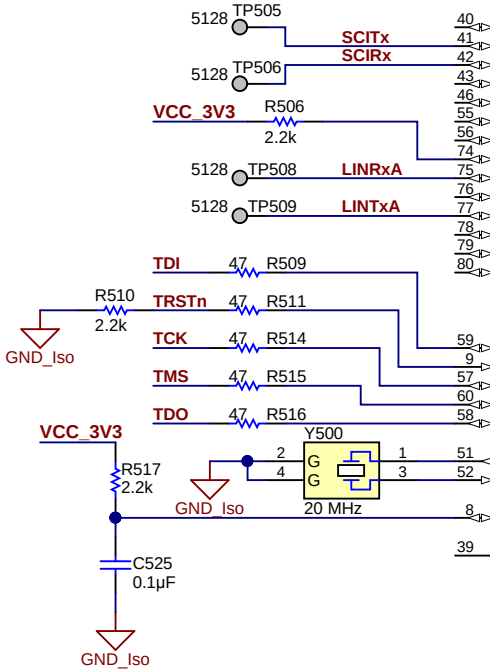
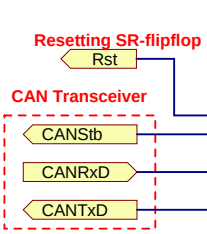
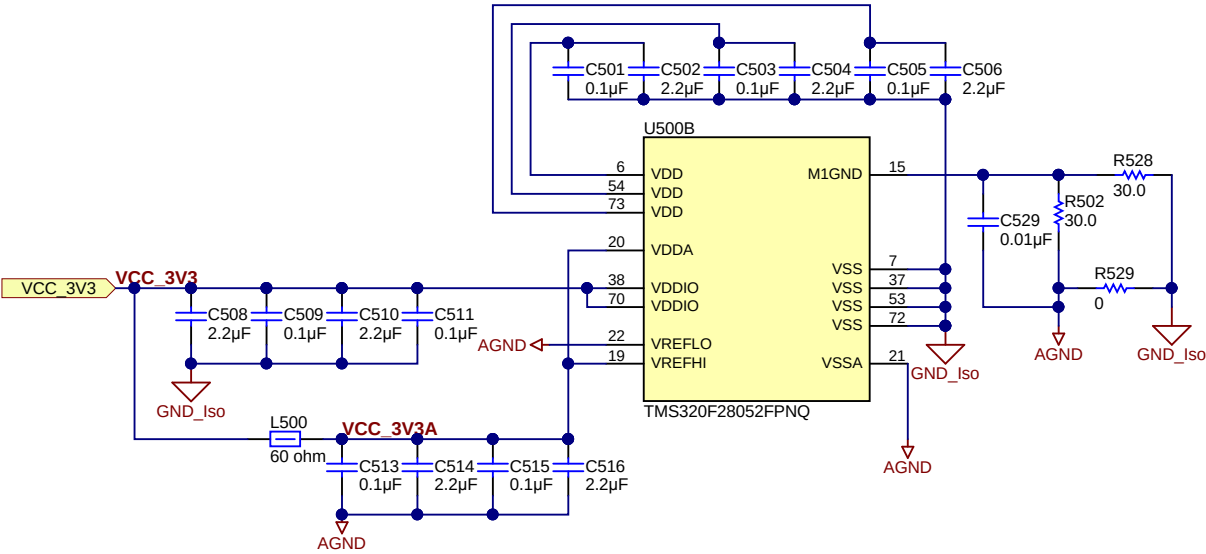


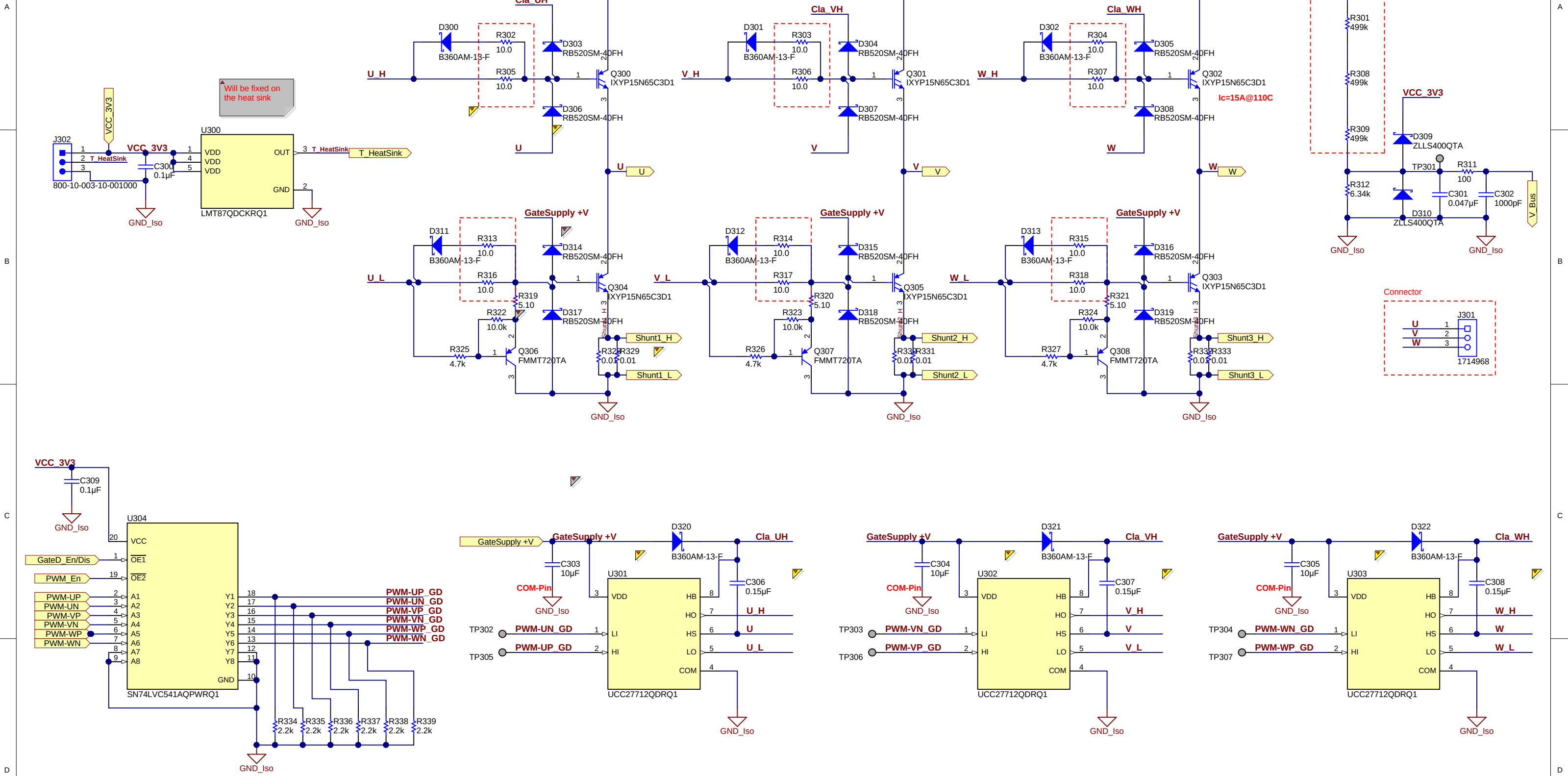
Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



5. MCU (C2000, Hot Side)



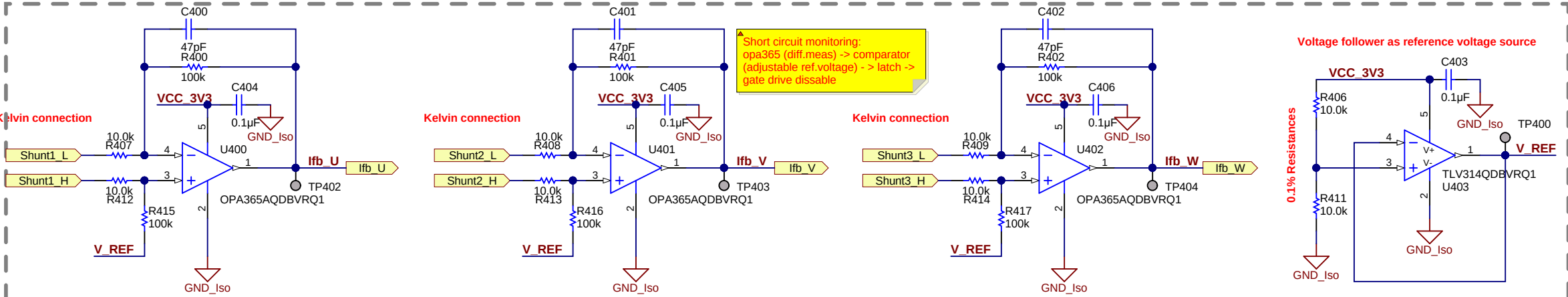
3. Power Module (IGBT, Gate driver, T-Sense)



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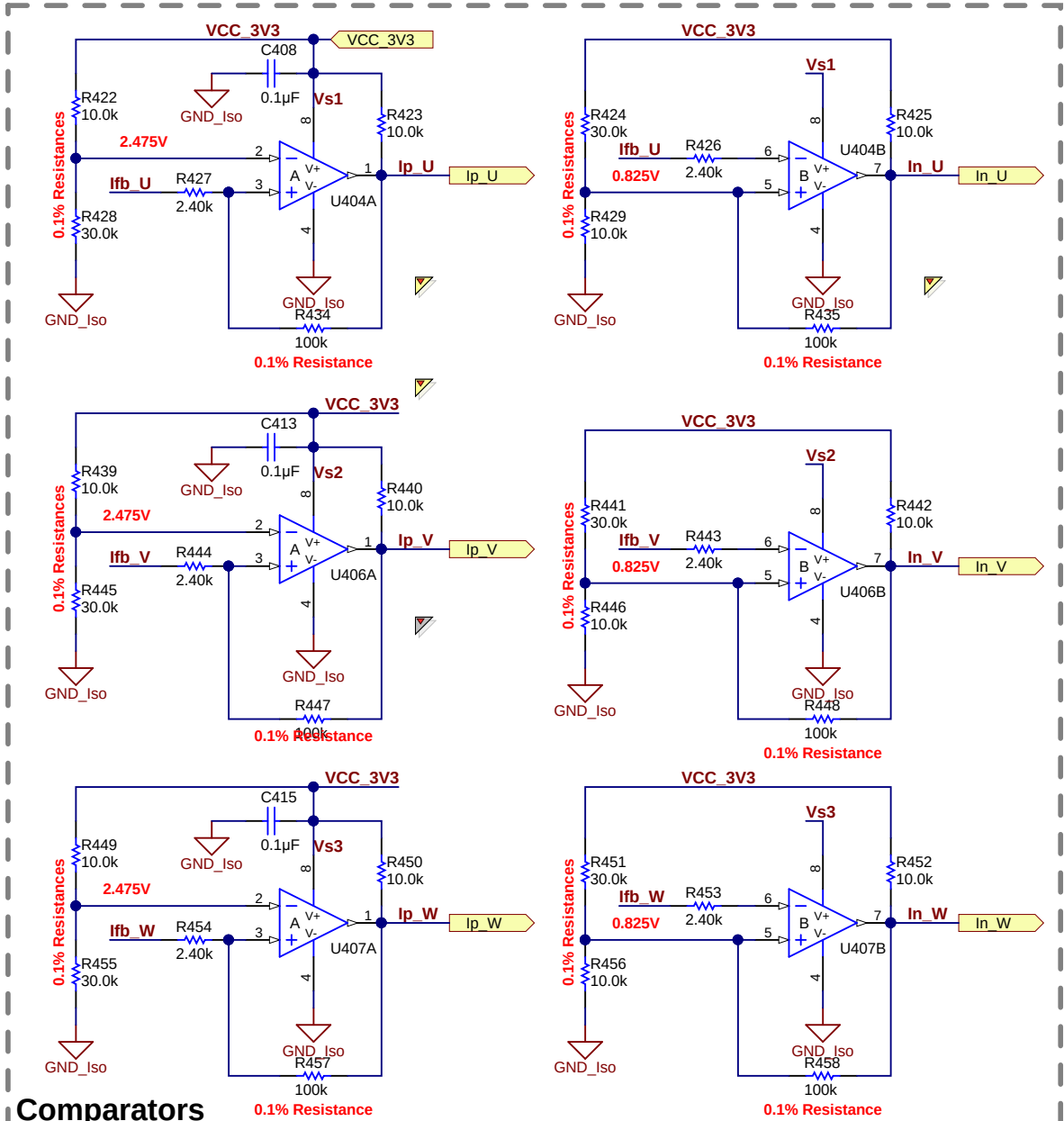
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TID #: TIDA-01418	Project Title: Automotive High Voltage, High Power Motor Drive	
Number: TIDA-01418	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 2 of 3
Drawn By:	File: TIDA-01418_IGBT_GateDrivers_UCC27712.Sch	Size: B
Engineer: Levan Bidzishvili	Contact: http://www.ti.com/support	

4. Current Sense, Voltage Feedback (Hot Side)

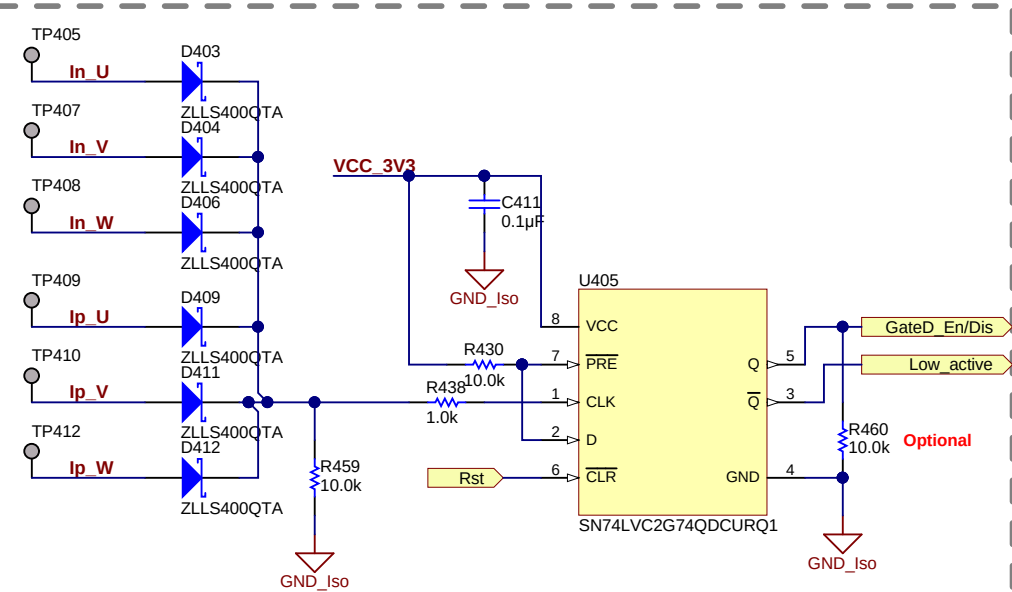


Differential Amplifiers

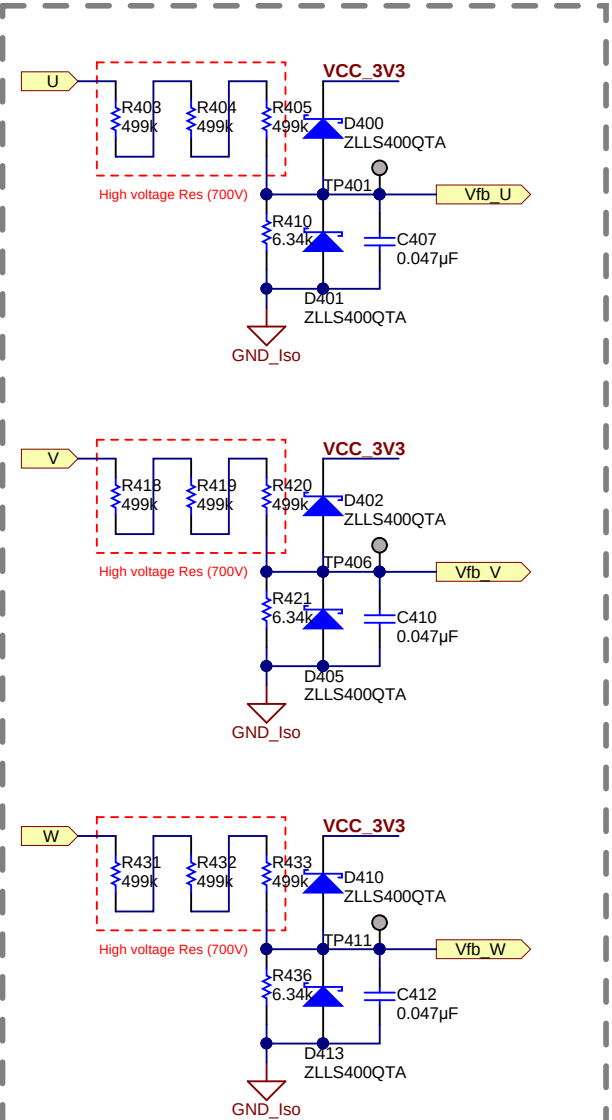
Voltage follower



Comparators

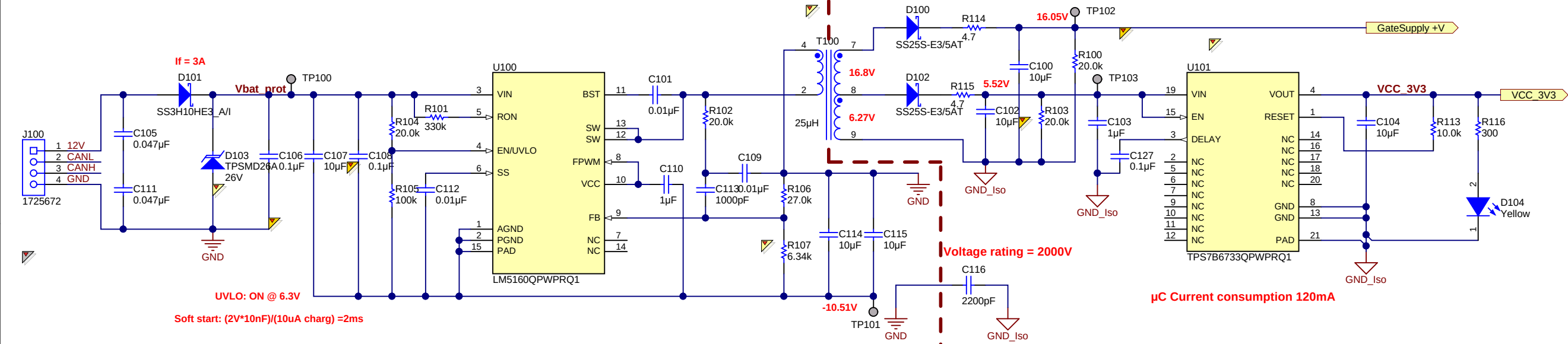


SR-Flipflop

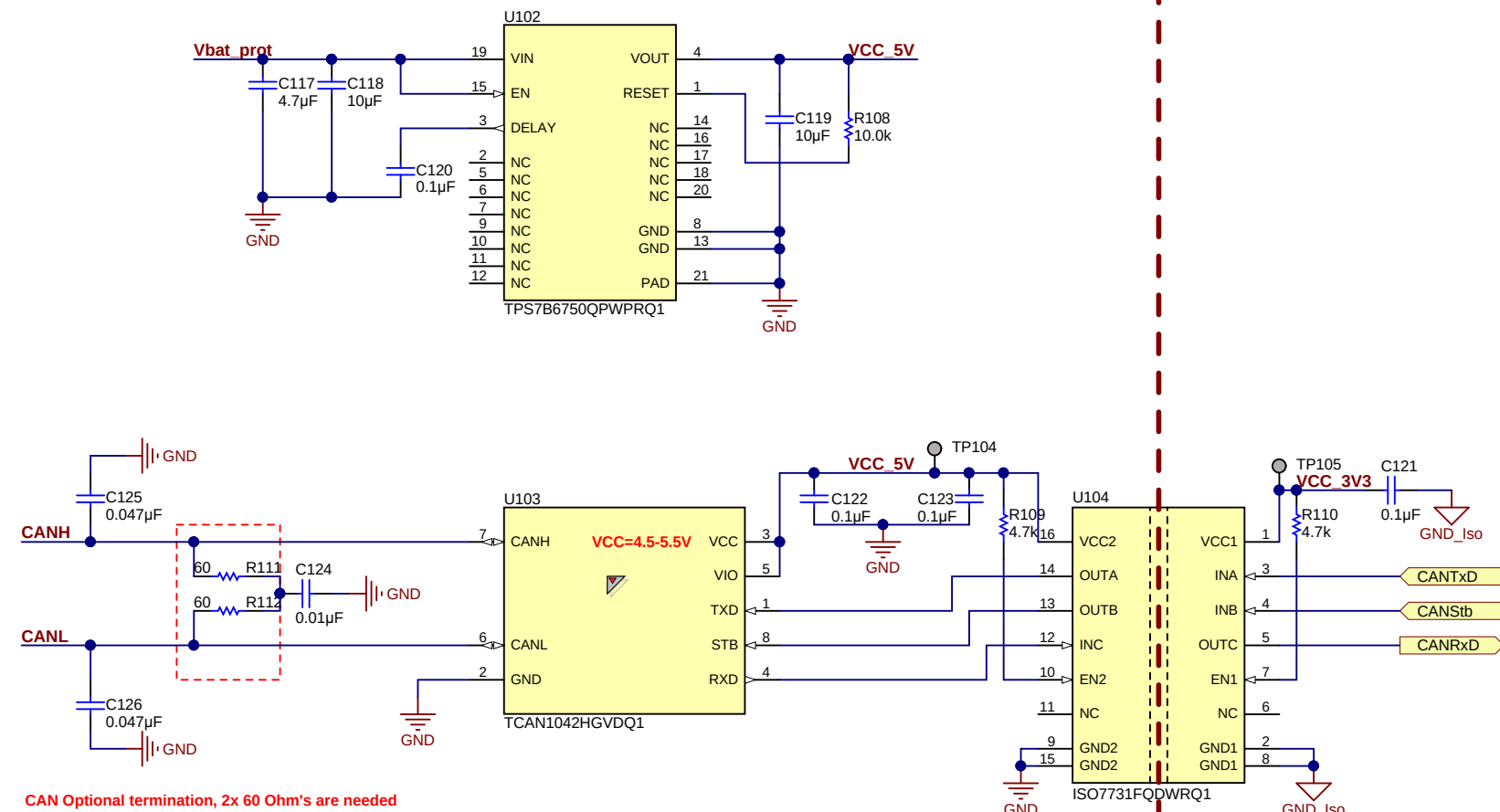


Voltage Feedback

1. Protection Circuit, Power Supply (Fly-Buck-Boost)



1.2. Communication (CAN), Power Supply (WD), Digital Isolation





NY PMS 440 0025 PH



NY PMS 440 0025 PH



NY PMS 440 0025 PH



NY PMS 440 0025 PH



1902C



1902C



1902C



1902C

PCB Number: TIDA-01418
PCB Rev: E1

PCB
LOGO
Texas Instruments

PCB
LOGO
Pb-Free Symbol

PCB
LOGO
FCC disclaimer

You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You should delete this note too.

Variant/Label Table

Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1

PCB Label

Size: 0.65" x 0.20 "

ZZ1

Label Assembly Note

This Assembly Note is for PCB labels only

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 9/14/2017	 TEXAS INSTRUMENTS http://www.ti.com © Texas Instruments 2016
TID #: TIDA-01418	Project Title: Automotive High Voltage, High Power Motor Drive for EV		
Number: TIDA-01418 [Rev: E1]	Sheet Title:		
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 3 of 3	
Drawn By:	File: TIDA-01418_EVM_Hardware.SchDoc	Size: B	
Engineer: Levan Bidzishvili	Contact: http://www.ti.com/support		

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